

KEPITAL[®] F20-03 LOF

A low-emission(medium-viscosity)grade for general injection molding.

- A low-emission(medium-viscosity)grade for general injection molding.

- Features improved heat stability

Rheological properties

Typical mechanical propertiesTensile Modulus2750MPaISO 527-1/-2Yield stress, 50mm/min65MPaISO 527-1/-2Yield strain, 50mm/min10 %ISO 527-1/-2Nominal strain at break35 %ISO 527-1/-2Flexural Modulus2550MPaISO 178Flexural Modulus2550MPaISO 178Charpy notched impact strength, 23 °C6.5 kJ/m²ISO 179/1eACharpy notched impact strength, -30 °C5.5 kJ/m²ISO 179/1eAChermal propertiesMelting temperature, 10 °C/min165 °CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100 °CISO 11357-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical propertiesSurface resistivity>1E15 OhmIEC 62631-3-2Electric strength19 kV/mmIEC 60243-1Other propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62	Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Yield stress, 50mm/min 65 MPa ISO 527-1/-2 Yield strain, 50mm/min 10 % ISO 527-1/-2 Nominal strain at break 35 % ISO 527-1/-2 Nominal strain at break 35 % ISO 527-1/-2 Flexural Modulus 2550 MPa ISO 527-1/-2 Flexural Modulus 2550 MPa ISO 178 Flexural Strength 87 MPa ISO 178 Charpy notched impact strength, 23 °C 6.5 kJ/m² ISO 179/1eA Charpy notched impact strength, -30 °C 5.5 kJ/m² ISO 179/1eA Charpy notched impact strength, -30 °C 5.5 kJ/m² ISO 179/1eA Charpy notched impact strength, -30 °C 5.5 kJ/m² ISO 11357-1/-3 Temp. of deflection under load, 1.8 MPa 100 °C ISO 11357-1/-2 Coeff. of linear therm. expansion, parallel 120 E-6/K ISO 11359-1/-2 Electrical properties Surface resistivity >1E15 Ohm IEC 62631-3-2 Electric strength 19 kV/mm IEC 60243-1 Other properties 19 kV/mm IEC 60243-1	Typical mechanical properties			
Yield strain, 50mm/min10 %ISO 527-1/-2Nominal strain at break35 %ISO 527-1/-2Flexural Modulus2550 MPaISO 527-1/-2Flexural Strength87 MPaISO 178Charpy notched impact strength, 23 °C6.5 kJ/m²ISO 179/1eACharpy notched impact strength, -30 °C5.5 kJ/m²ISO 179/1eAThermal propertiesMelting temperature, 10 °C/min165 °CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100 °CISO 75-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical propertiesSurface resistivity>1E15 OhmIEC 62631-3-2Electric strength19 kV/mmIEC 60243-1Other propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62	Tensile Modulus	2750	MPa	ISO 527-1/-2
Nominal strain at break35 %ISO 527-1/-2Flexural Modulus2550MPaISO 178Flexural Strength87MPaISO 178Charpy notched impact strength, 23 °C6.5 kJ/m²ISO 179/1eACharpy notched impact strength, -30 °C5.5 kJ/m²ISO 179/1eAThermal propertiesMelting temperature, 10 °C/min165 °CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100 °CISO 75-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical propertiesSurface resistivity Electric strength>1E15 OhmIEC 62631-3-2 19 kV/mmOther propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62	Yield stress, 50mm/min	65	MPa	ISO 527-1/-2
Flexural Modulus2550MPaISO 178Flexural Strength87MPaISO 178Charpy notched impact strength, 23 °C6.5kJ/m²ISO 179/1eACharpy notched impact strength, -30 °C5.5kJ/m²ISO 179/1eAThermal propertiesMelting temperature, 10 °C/min165°CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100°CISO 11357-1/-2Coeff. of linear therm. expansion, parallel120E-6/KISO 11359-1/-2Electrical propertiesSurface resistivity Electric strength>1E15OhmIEC 62631-3-2Electric strength19kV/mmIEC 60243-1Other propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62	Yield strain, 50mm/min	10	%	ISO 527-1/-2
Flexural Strength87MPaISO 178Charpy notched impact strength, 23 °C6.5kJ/m²ISO 179/1eACharpy notched impact strength, -30 °C5.5kJ/m²ISO 179/1eAThermal propertiesMelting temperature, 10 °C/min165°CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100°CISO 75-1/-2Coeff. of linear therm. expansion, parallel120E-6/KISO 11359-1/-2Electrical propertiesSurface resistivity Electric strength>1E15OhmIEC 62631-3-2 IEC 60243-1Other propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62	Nominal strain at break	35	%	ISO 527-1/-2
Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C6.5 kJ/m²ISO 179/1eAThermal propertiesMelting temperature, 10°C/min Temp. of deflection under load, 1.8 MPa Coeff. of linear therm. expansion, parallel165 °C 100 °C 1SO 75-1/-2 120 E-6/KISO 11357-1/-3 1SO 75-1/-2Electrical propertiesSurface resistivity Electric strength>1E15 Ohm 19 kV/mmIEC 62631-3-2 19 kV/mmOther propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62	Flexural Modulus	2550	MPa	ISO 178
Charpy notched impact strength, -30 °C5.5 kJ/m²ISO 179/1eAThermal propertiesMelting temperature, 10 °C/min165 °CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100 °CISO 75-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical propertiesSurface resistivity>1E15 OhmIEC 62631-3-2Electric strength19 kV/mmIEC 60243-1Other propertiesHumidity absorption, 2mm0.2 %	Flexural Strength	87	MPa	ISO 178
Thermal propertiesMelting temperature, 10°C/min165 °CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100 °CISO 75-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical propertiesSurface resistivity>1E15 OhmIEC 62631-3-2Electric strength19 kV/mmIEC 60243-1Other propertiesHumidity absorption, 2mm0.2 %Sim. to ISO 62				
Melting temperature, 10 °C/min165 °CISO 11357-1/-3Temp. of deflection under load, 1.8 MPa100 °CISO 75-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical properties>1E15 OhmIEC 62631-3-2Surface resistivity>19 kV/mmIEC 60243-1Other properties0.2 %Sim. to ISO 62	Charpy notched impact strength, -30°C	5.5	kJ/m²	ISO 179/1eA
Temp. of deflection under load, 1.8 MPa100 °CISO 75-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical properties>1E15 OhmIEC 62631-3-2Surface resistivity Electric strength>1E15 OhmIEC 62631-3-2Other properties19 kV/mmIEC 60243-1Other properties0.2 %Sim. to ISO 62	Thermal properties			
Temp. of deflection under load, 1.8 MPa100 °CISO 75-1/-2Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical properties>1E15 OhmIEC 62631-3-2Surface resistivity>1E15 OhmIEC 62631-3-2Electric strength19 kV/mmIEC 60243-1Other properties0.2 %Sim. to ISO 62	Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Coeff. of linear therm. expansion, parallel120 E-6/KISO 11359-1/-2Electrical properties>1E15 Ohm 19 kV/mmIEC 62631-3-2 IEC 60243-1Other properties0.2 %Sim. to ISO 62	o .	100	°C	ISO 75-1/-2
Surface resistivity Electric strength>1E15 Ohm 19 kV/mmIEC 62631-3-2 IEC 60243-1Other properties Humidity absorption, 2mm0.2 %Sim. to ISO 62		120	E-6/K	ISO 11359-1/-2
Electric strength19 kV/mmIEC 60243-1Other properties0.2 %Sim. to ISO 62	Electrical properties			
Electric strength19 kV/mmIEC 60243-1Other properties0.2 %Sim. to ISO 62	Surface resistivity	>1E15	Ohm	IEC 62631-3-2
Humidity absorption, 2mm0.2 %Sim. to ISO 62	•			
	Other properties			
	Humidity absorption. 2mm	0.2	%	Sim. to ISO 62
Density 1410 kg/m ³ ISO 1183	, .			

Other Approvals

Other Approvals

OEM	Specification	Additional Information
GM	GMW22P-POM-C2	
GM	GMW17008P-POM-C2	Black
Ford	WSK-M4D635-A2	ASN 3094
Stellantis - PSA Group	B62 0020	



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